



SCIENTECH

Sciencetech Corp.

MT Hsu 2026/09/03

- **This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.**
- **Except as required by law, we undertake no obligation to update any forward-looking statements, whether as a result of new information, future events or otherwise.**

Agenda



About Us

Overview | Milestones | Location | Organization





Product and Technology

- Equipment Design and Manufacturing
- Wafer Reclaim
- Representative



Industries We Serve

- Semiconductor (Front-End and Advanced Packaging)
- Compound Semiconductor
- LED / Mini LED / Micro LED
- Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)
- IC Package Substrate



Established:
1979
Taipei, Taiwan

Capital:
US\$ 27 Million
TWSE:3583

Employees:
>1,150
(World wide)

Employees

Over 1,150 Employees

Representative

- 135 in Taiwan
- 130 in China
- 70% in Service and Process Support

Equipment Design and Maf'g

- 450 in Total
- 130+ in R&D, Process and Design

Wafer Reclaim

- 335 in Total

Administration

- 105 in Total

Milestones



SCIENTECH
1979



1985

Branch Office
in Hsinchu, Taiwan



1995

Subsidiary
in CA, USA



2001

Subsidiary
in Shanghai, China



2002

Singapore



2003

Equipment Manufacture
Department Established

2025

Over 1000 Equipment Sales Achievement



2021

Subsidiary
in Villach, Austria



2013

Publicly Listed in
Taiwan Stock Market



2007

New Factory
in Hukou Opened



2006

Wafer Reclaim
Business Launched



2004

New Hsinchu
Office Opened



Locations - Taiwan

Taipei Headquarter

HsinChu Office

HuKou Factory

- Equipment Design and Manufacturing
 - ◆ Equipped With Class 10/1,000/10,000 Clean Room
- Wafer Reclaim



Taichung Office

Chiayi Office

Tainan Office

Kaohsiung Office

Locations - Worldwide

Europe

Villach, Austria (2020)

- Sales and Service Office to support European customers
- Interface with our factory and European Customers
- New Product / PRODUCTS Development

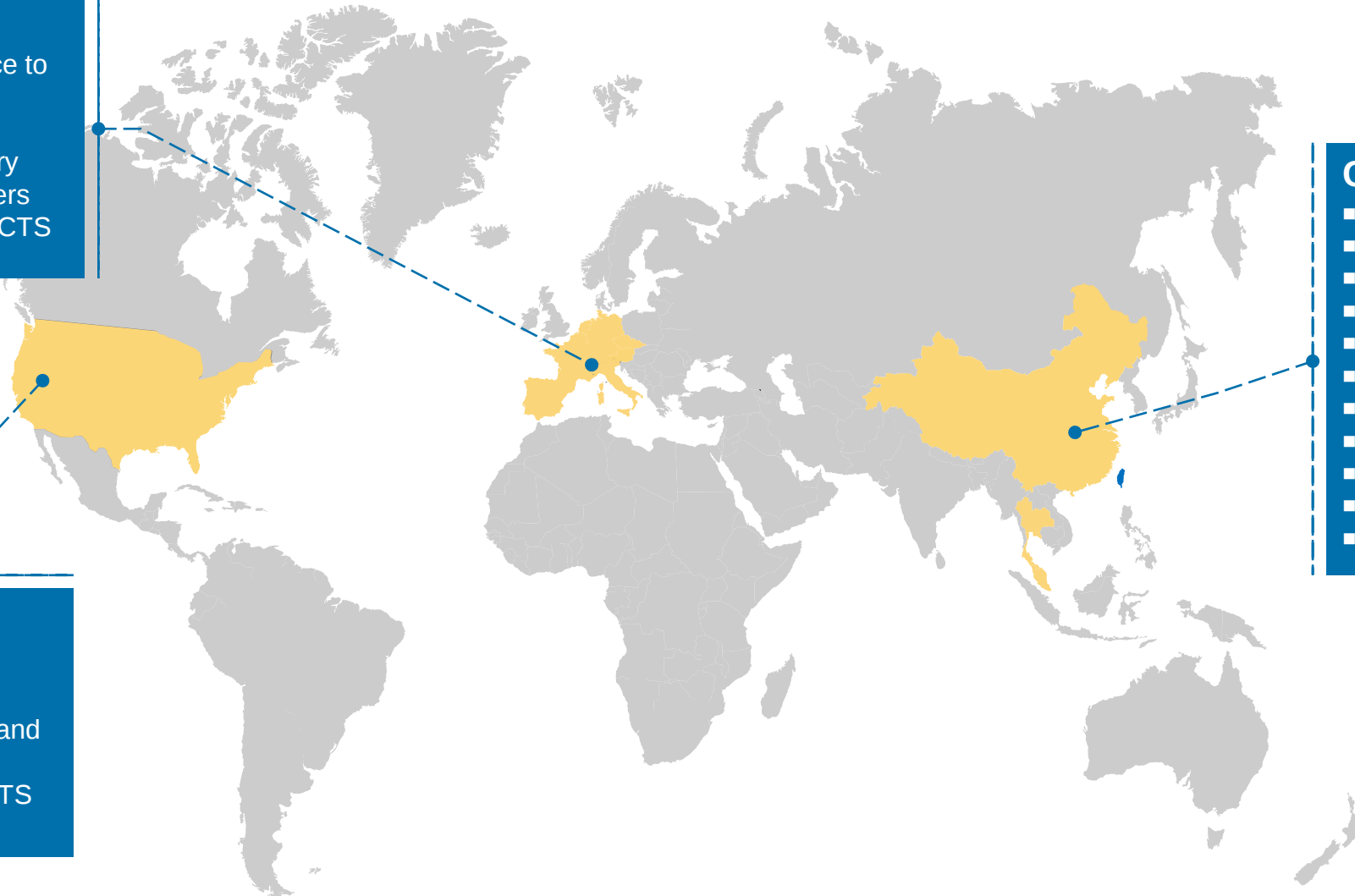
China

- Beijing office (2004)
- Dalian office (2012)
- Xian (2013)
- Chongqing office (2010)
- Changzhou (2012)
- Wuxi office (2003)
- Shanghai Office (2001)
- Wuhu office (2013)
- Xiamen office (2011)
- Huizhou office (2013)
- Qunming Office (2002)

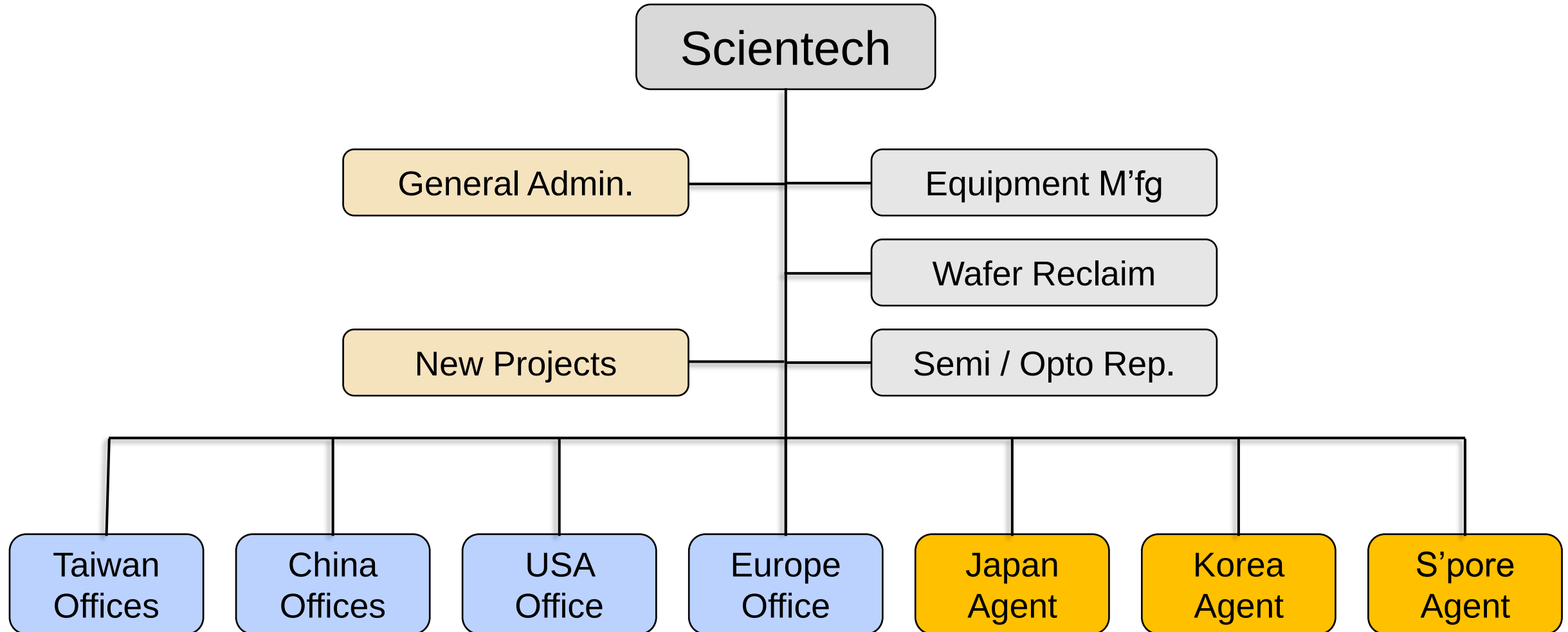
USA

Santa Clara, CA (1994)

- Sales and Service Office
- Interface with Principals and U.S. Customers
- New Product / PRODUCTS Development



Organization



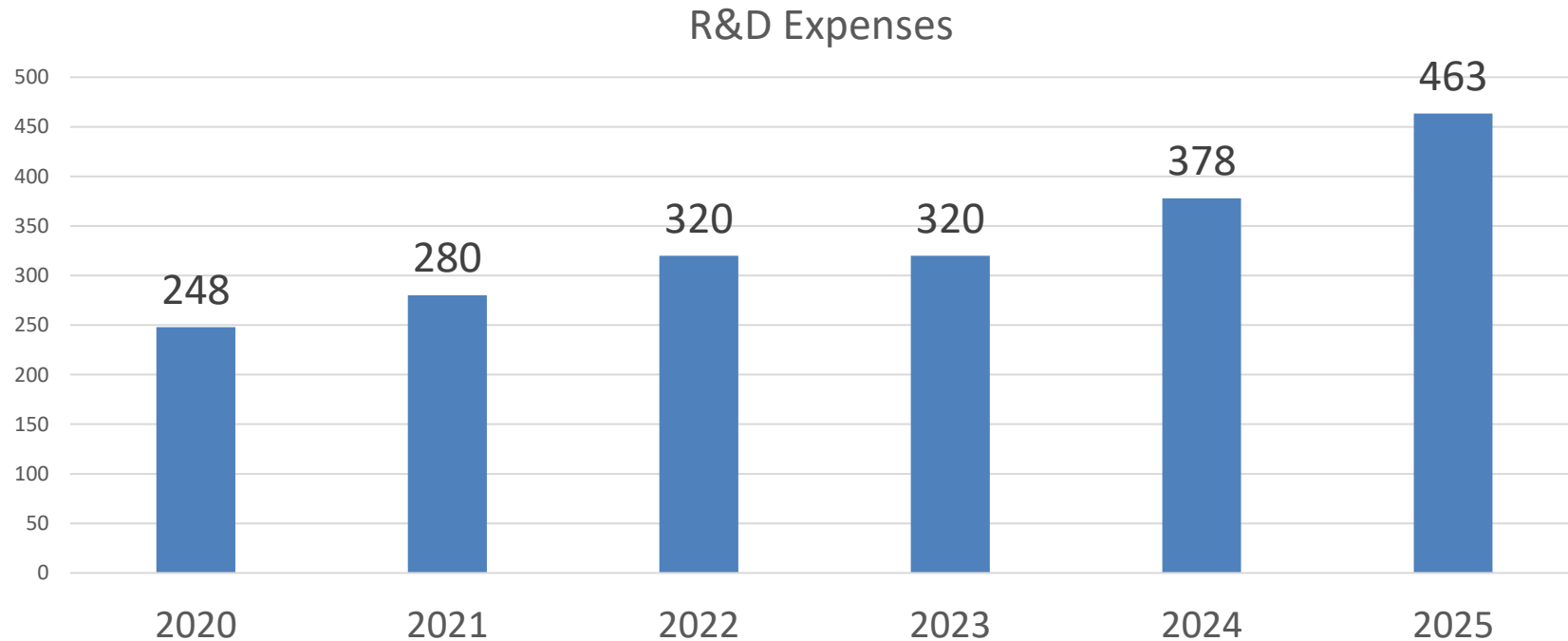
Products & Services

Wafer Reclaim | Equipment Manufacturing and Design |
Representative

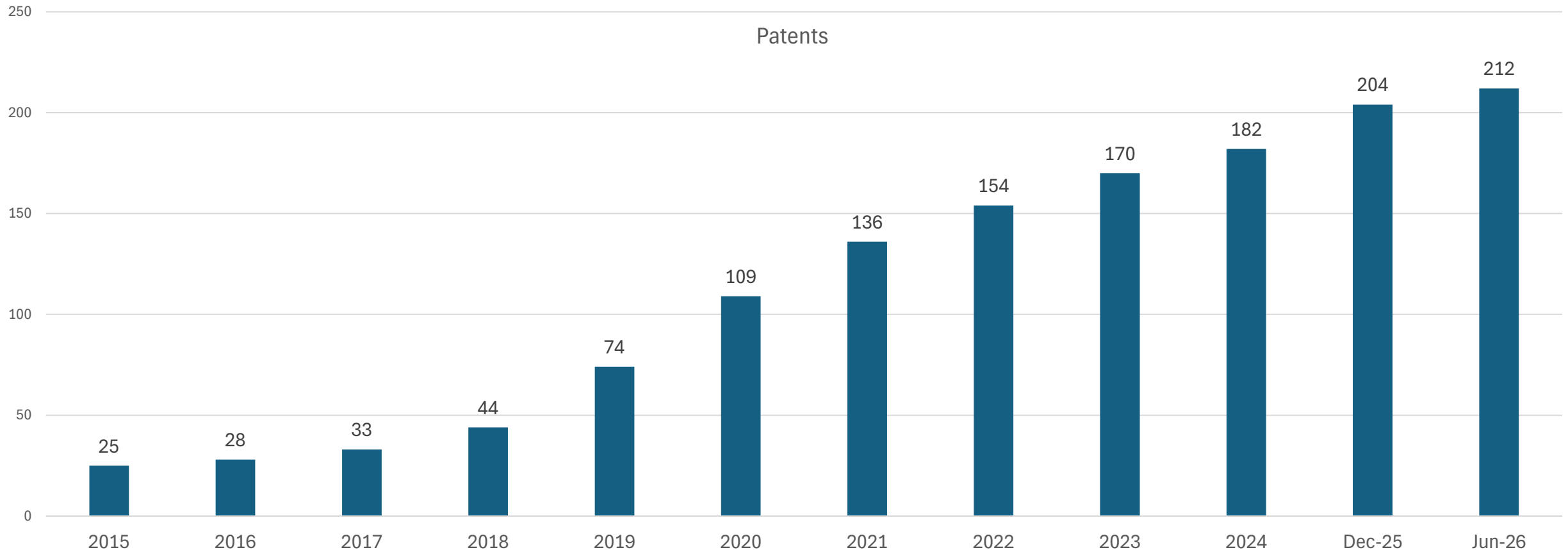


R&D Expenses

Units : NT \$ M	2020	2021	2022	2023	2024	2025	2026/Q2
R&D Expenses	248	280	320	320	378	463	314
Expenses as % of Revenue	6.9%	6.0%	5.7%	5.7%	3.9%	4.1%	5.1%
Expenses as % of Manufacturing	16.5%	14.9%	15.3%	15.7%	11.3%	9.8%	10.0%



- The cumulative number of patents on file is 212, and 50 applications are pending.



Products



Equipment Design and Manufacturing

- Advanced Package
- FEOL
- Mask
- Compound
- etc...



Wafer Reclaim

- 12" Si Wafer



Representative

- Equipment/Metrology
- Sub-System
- Material
- Repair and Refurbish

Wafer Reclaim Service

Advanced Clean Technology

- 19nm Particle
- Low Trace Metal (<1E9)



Advanced Defect Inspection (SP1/SP2/SP5/SP7)

Etching



Capacity Expansion

- Additional 40K / Month by end of 2026



12" Si Wafer

- Capacity: 210K / Month
- Cu and Non-Cu Process



Cleaning

Full Process Optimization

Polishing

Complete Polishing Process

- Single/Double Side Polish
- Final Haze Polish



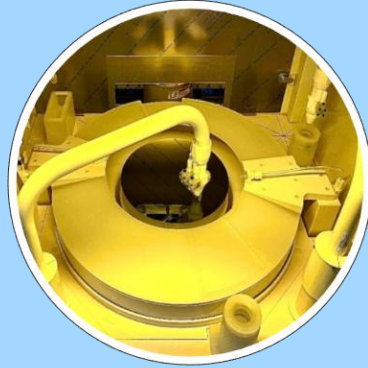
Grinding

Super Flatness (GBIR < 0.5mm)

Equipment Design & MFG



Wet Bench



Wet Single Wafer



TBDB



Baking

Wet Process – Bench

Application

- Semiconductor: FEOL, BEOL, Compound
- Advanced Packaging/Bumping...

Features

- Cassette type or Cassette-less type
- Adopted by big international companies
- Leading-edge technologies

Process

- Etch: Metal/Oxide/Nitride remove
- Stripper: PR/PI strip, Polymer remove
- Clean: Pre/Post/Flux clean
- Electro-less Plating: Zn/Ni/Pd/Au



Wet Process – Single Wafer

Application

- Semiconductor: BEOL, FEOL, Compound
- Advanced Packaging/Bumping

Features

- Soak/Immersion + Single
- Adopted by big international companies
- Leading-edge technologies

Process

- UBM / Metal Etch
- Flux Clean (Hot DIW)
- PR Strip
- Wafer Clean (APC, Soft spray)
- Final Clean/Mask Clean/Frame Clean



Temporary Bonding De-Bonding

Application

- IGBT & SiC Power Device
- Advanced Packaging for Semiconductor

Features

- User-friendly graphical user interface
- Adopted by big international companies
- Leading-edge technologies

Process

- Temporary Bonding
- Temporary De-bonding
- Release Layer Coating
- Carrier (Glass) Recycling



Moisture Baking

Application

- Semiconductor: BEOL
- Advanced Packaging for Semiconductor

Features

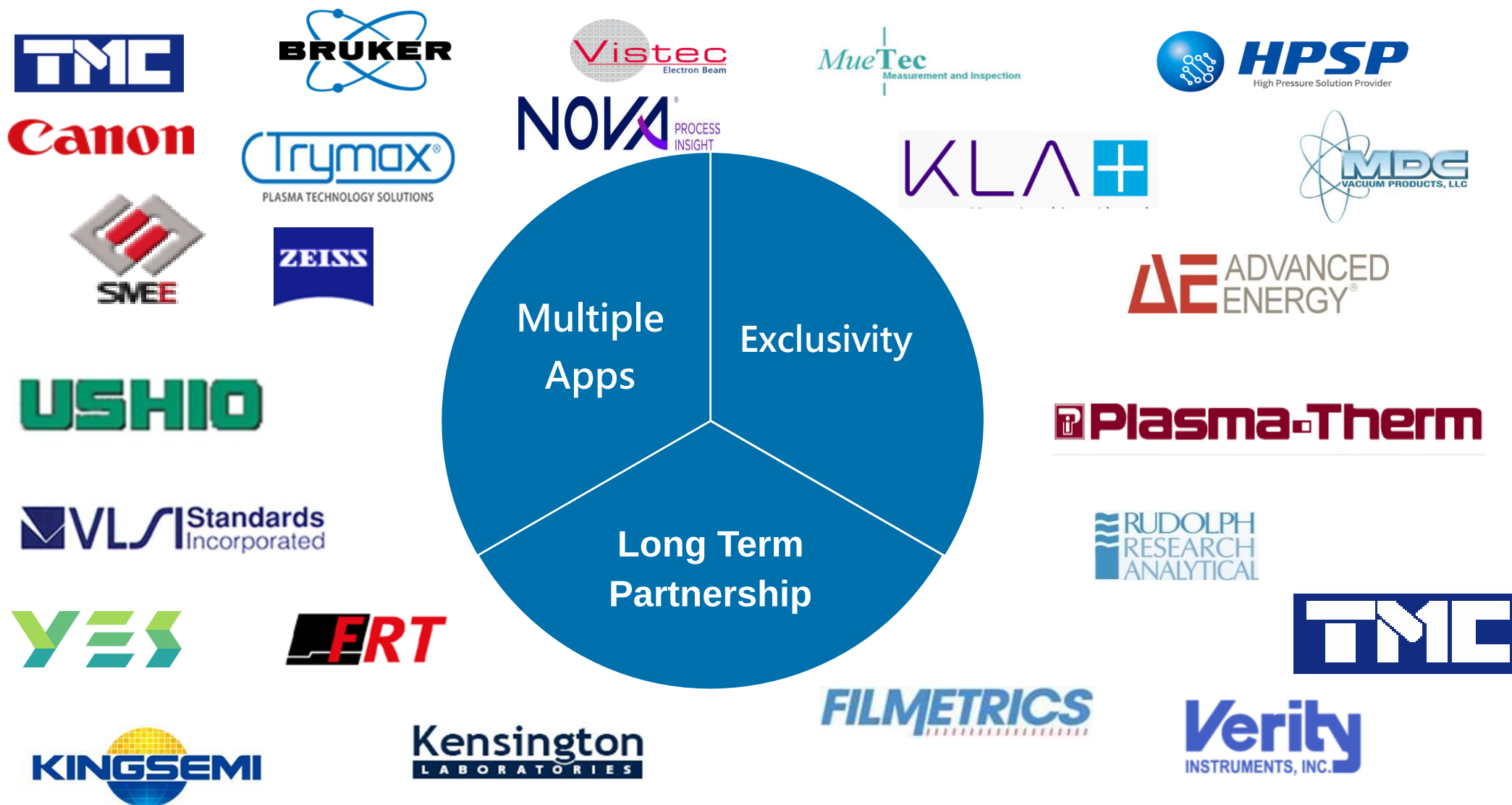
- Availability for horizontal or vertical process
- High precision temperature control
- Weight handling capacity up to 23kg per lot

Process

- Pre-underfill baking
- Pre-mold baking
- DFR Hard Bake



Trading (Agent/Distributor)



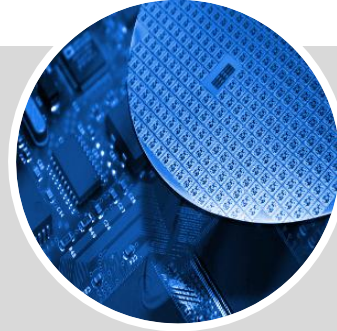
Representative Product Lines



Lithography



Etch



Thin Film



Diffusion



Representative Product Lines



Metrology

Sub-Systems

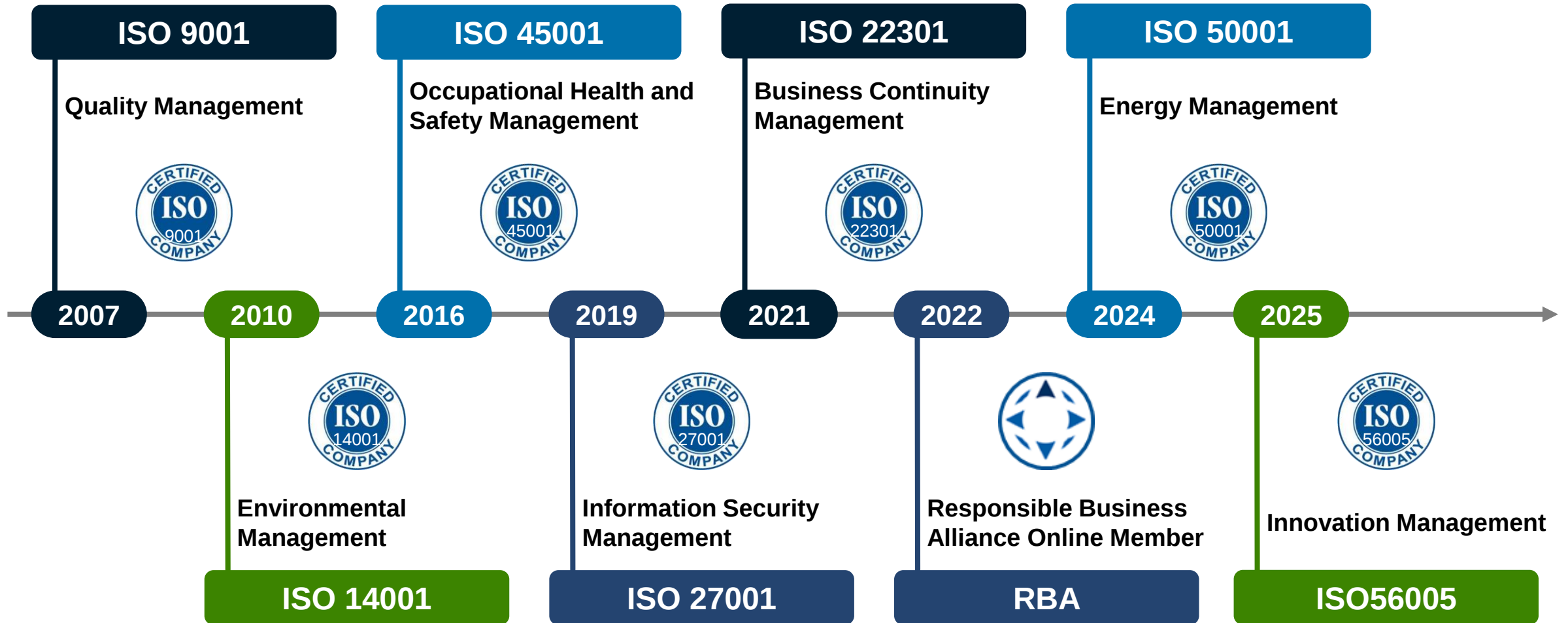
Package & Material

Robot Repair and Refurbish

Corporate Governance



Certificates



Sustainability Report Officially Released since 2024/08



**Eco-Friendly
Manufacturing**



**Safe And Warm
Working Environment**



**Operating With
Integrity**



**Contributing
To Society**



SEMICON®

Semicon China

Mar. 25-27, 2026
Shanghai



SEMICON®

Semicon TW

Sep. 2-4, 2026
Taipei



SEMICON®

Semicon West

Oct. 13-15, 2026
San Francisco



SEMICON®

Semicon Europa

Nov. 10-13, 2026
Munich

Exhibition



ISES

May 12-15, 2026
Taipei



ECTC

May 26-29, 2026
Orlando, Florida

Financial Results



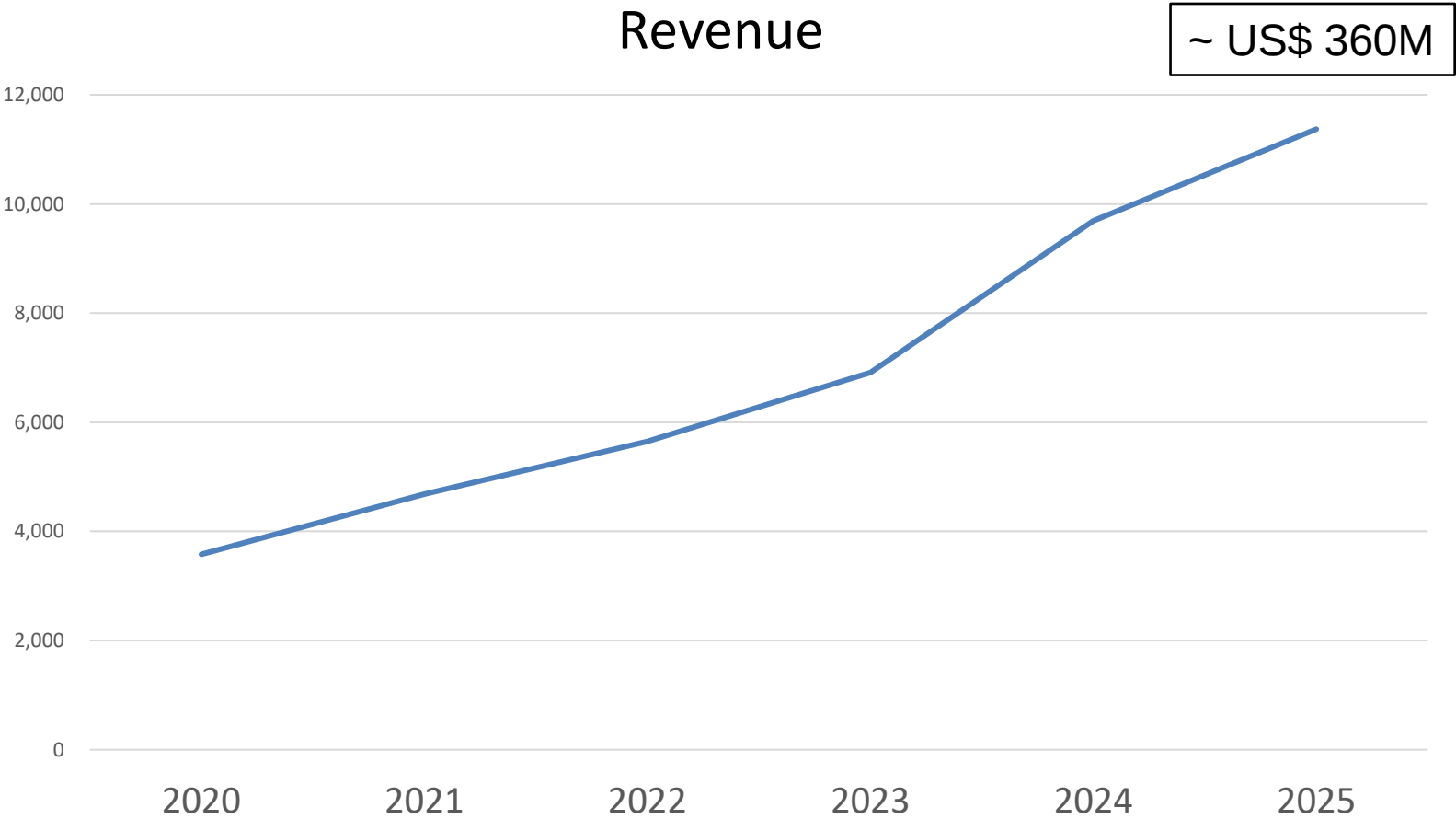
Income Statement

Units : NT \$ M	2020	2021	2022	2023	2024	2025	2026/Q2
Revenues	3,580	4,684	5,650	6,911	9,688	11,371	6,115
Gross Profit	1,456	1,667	2,084	2,201	2,906	3,814	2,256
Operating Expenses	991	1,112	1,374	1,483	1,790	2,238	1,349
Operating Income	465	555	710	718	1116	1,576	908
Income Before Tax	389	524	736	860	1277	1,540	958
Net profit attributable to: Owners of the Company	305	420	568	650	927	1,110	739
EPS	3.80	5.23	7.08	8.10	<u>11.54</u>	<u>13.82</u>	<u>9.16</u>
Gross Margin	41%	36%	37%	32%	30%	34%	37%
Operating Margin	13%	12%	13%	10%	12%	14%	15%
Income Before Tax Margin	11%	11%	13%	12%	13%	14%	16%

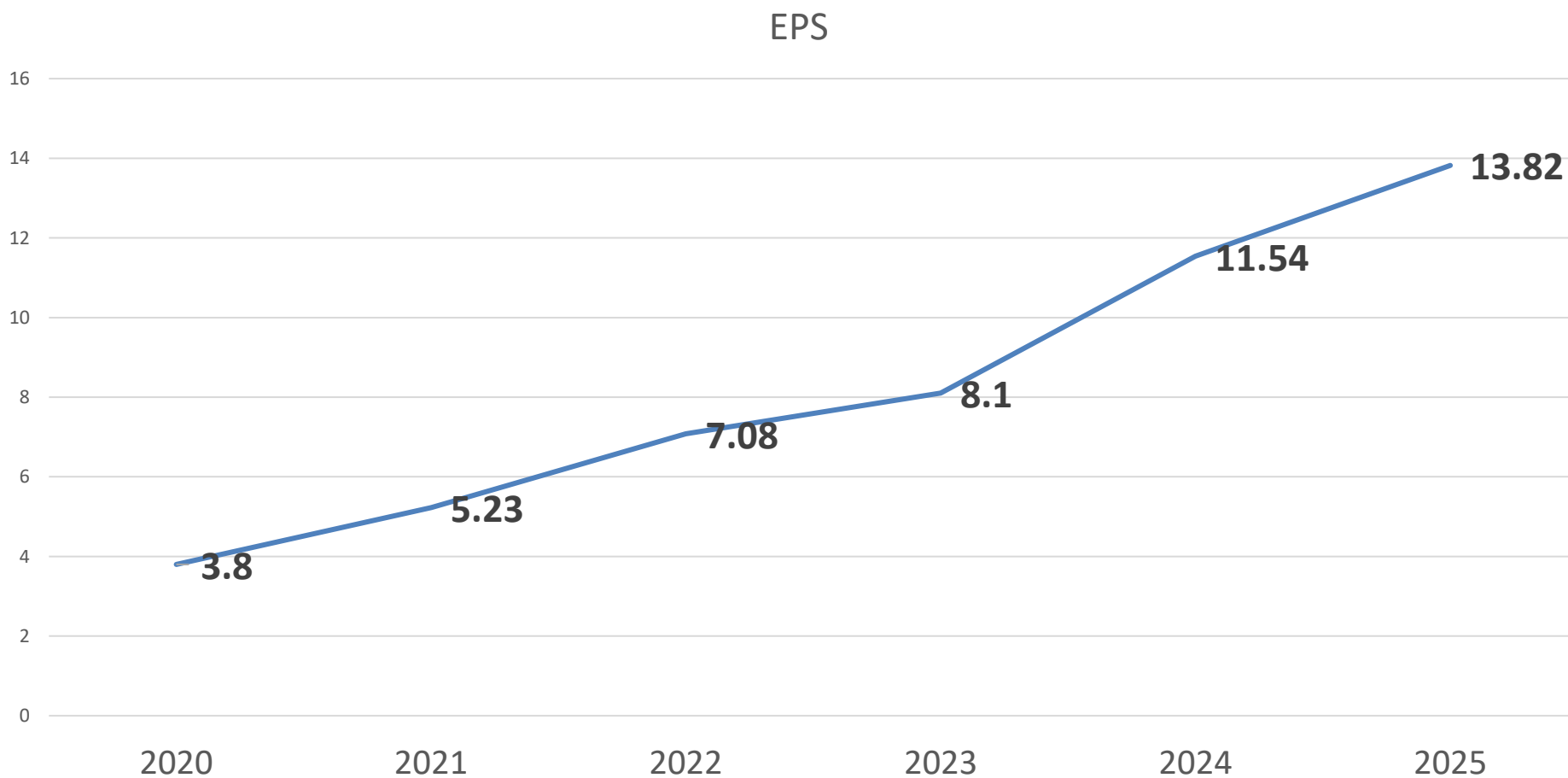
Annual Revenue



Units NT \$ M	2020	2021	2022	2023	2024	2025	2025/Q2	2026/Q2
Revenue	3,580	4,684	5,650	6,911	9,688	11,372	5,726	6,115



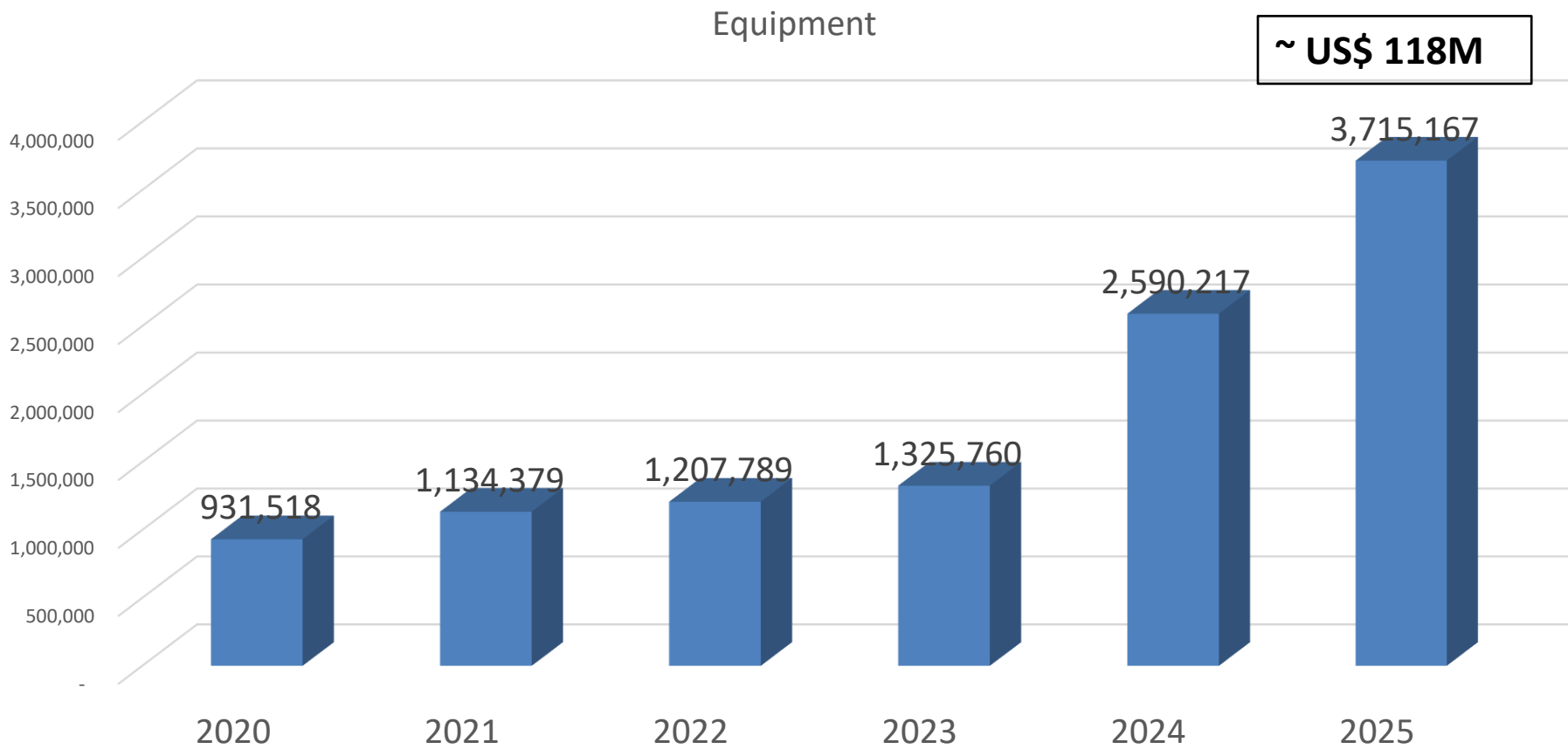
UNIT : NTD	2020	2021	2022	2023	2024	2025	2026/Q2
EPS	3.80	5.23	7.08	8.10	11.54	13.82	9.16



Equipment Revenue



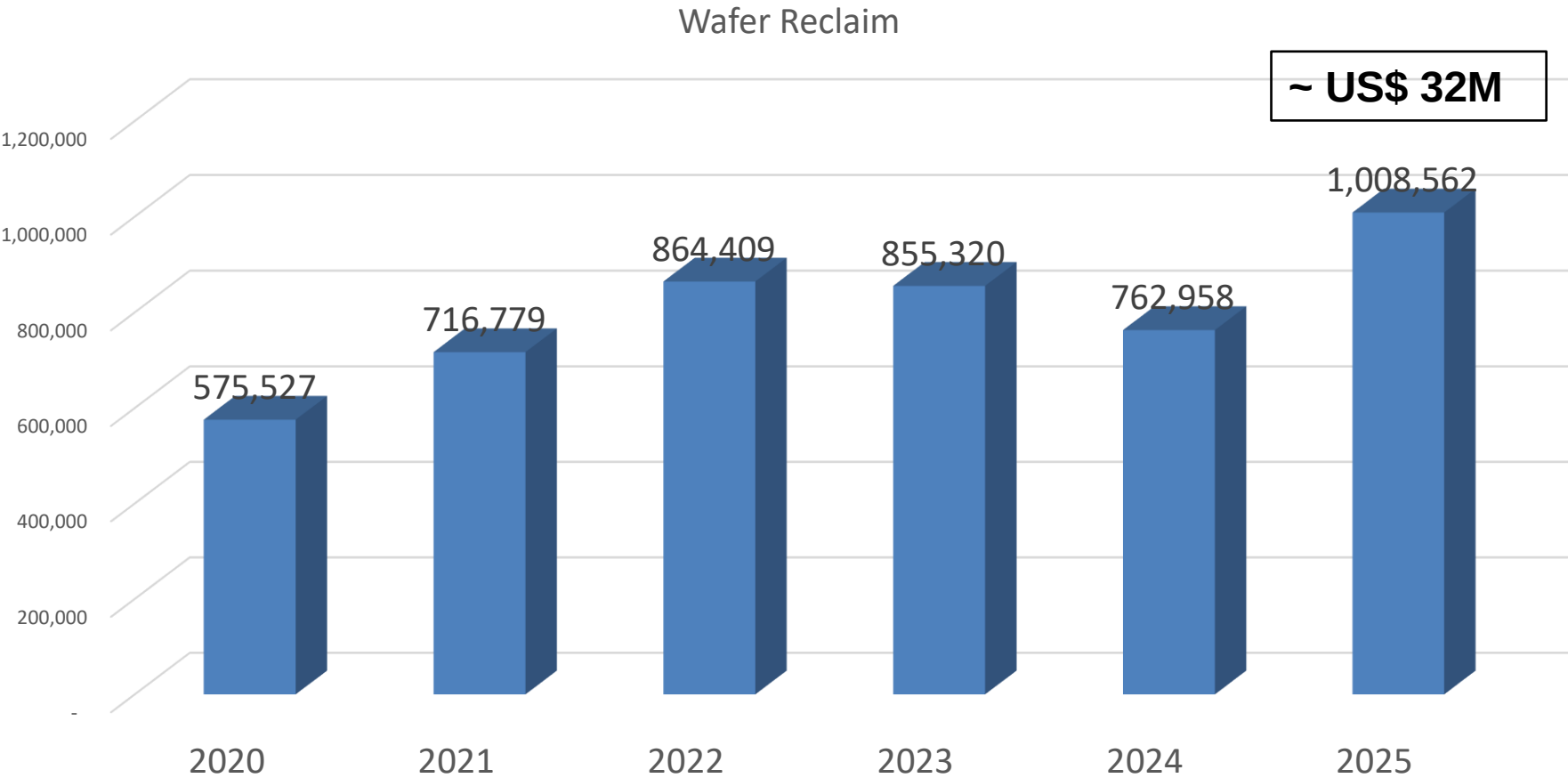
SALES Units NT \$ K	2020	2021	2022	2023	2024	2025	2026/Q2	2026
Equipment	931,518	1,134,379	1,207,789	1,325,760	2,590,217	3,715,167	2,562,617	



Wafer Reclaim Revenue



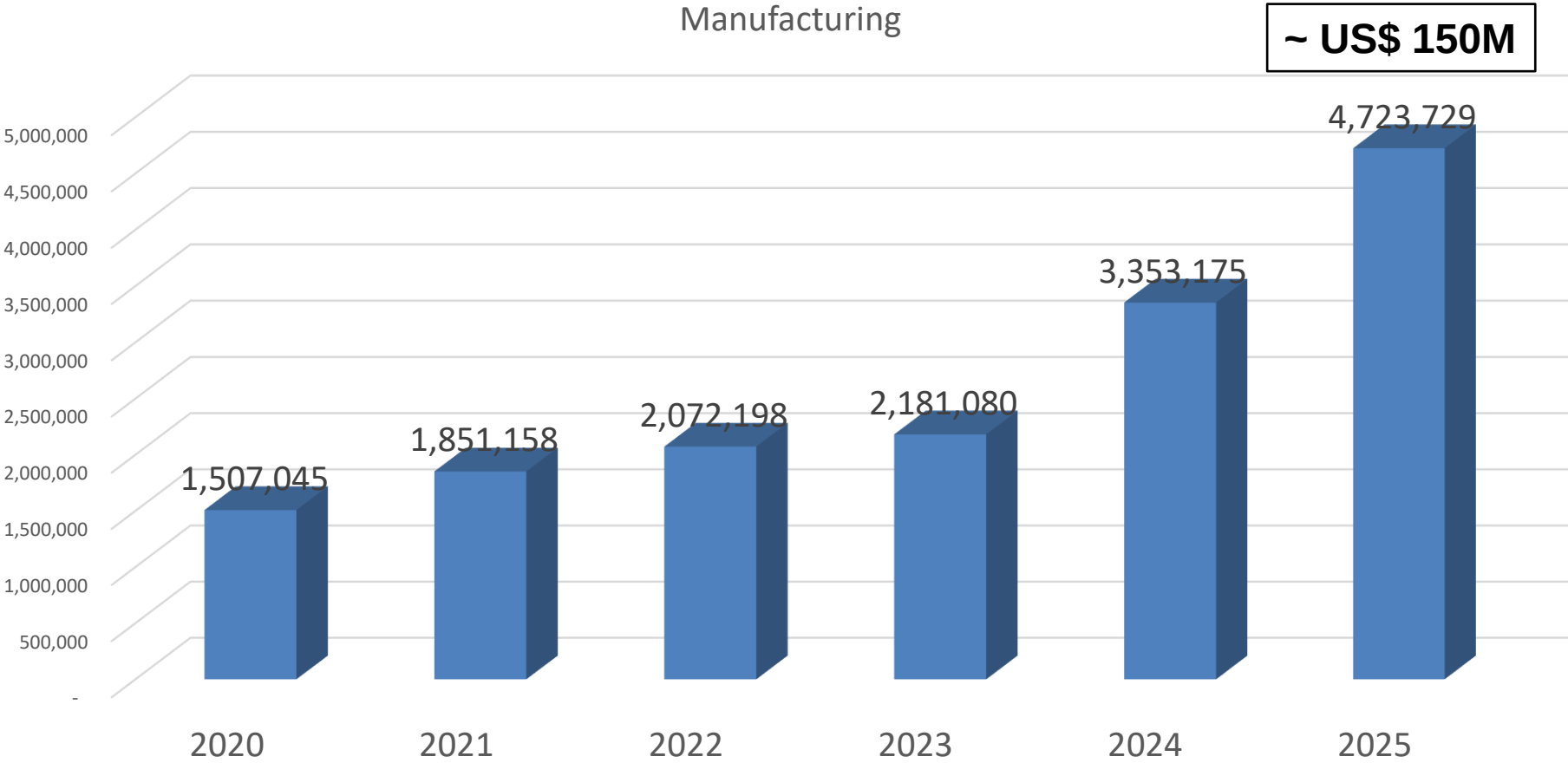
SALES Units NT \$ K	2020	2021	2022	2023	2024	2025	2026/Q2	2026
Wafer Reclaim	575,527	716,779	864,409	855,320	762,958	1,008,562	594,674	



Manufacturing Revenue



SALES Units NT \$ K	2020	2021	2022	2023	2024	2025	2026/Q2	2026
Manufacturing	1,507,045	1,851,158	2,072,198	2,181,080	3,353,175	4,723,729	3,157,291	



Trading Revenue



SALES Units NT \$ K	2020	2021	2022	2023	2024	2025	2026/Q2	2026
Trading	2,072,958	2,832,629	3,577,788	4,730,901	6,335,105	6,647,828	2,958,074	

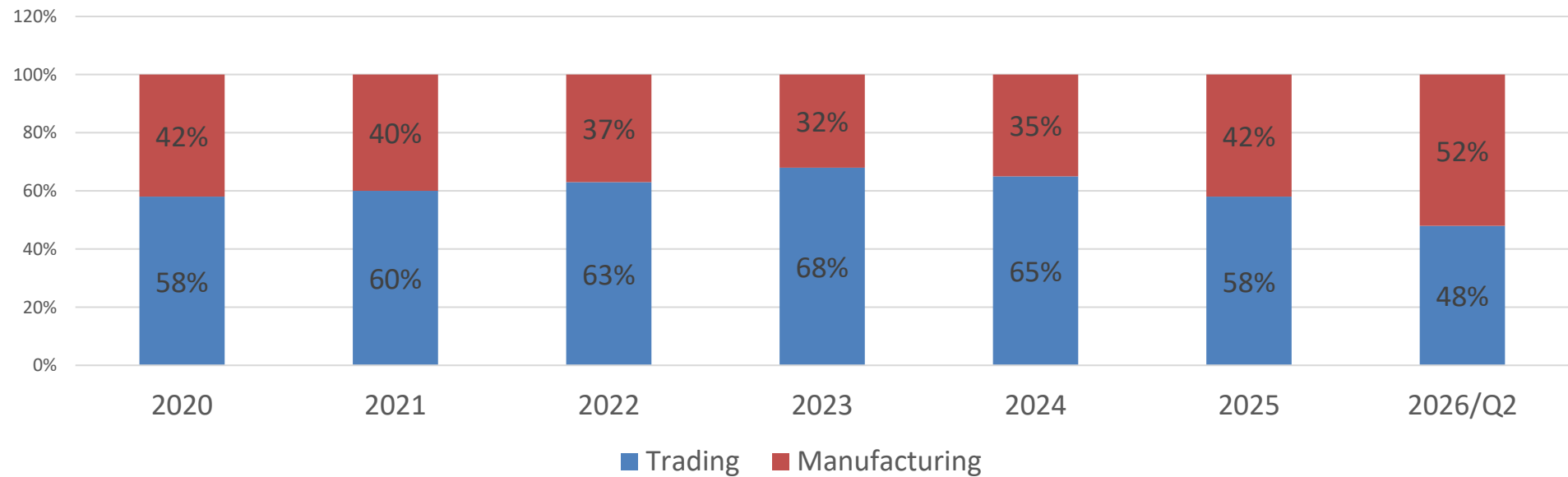


Products Mix – Revenue



Units : %	2020	2021	2022	2023	2024	2025	2026/Q2	2026	Gross Margin
Trading	58	60	63	68	65	58	48	<50%	Below Average
Manufacturing	42	40	37	32	35	42	52	>50%	Above Average

Revenue



Future Outlook

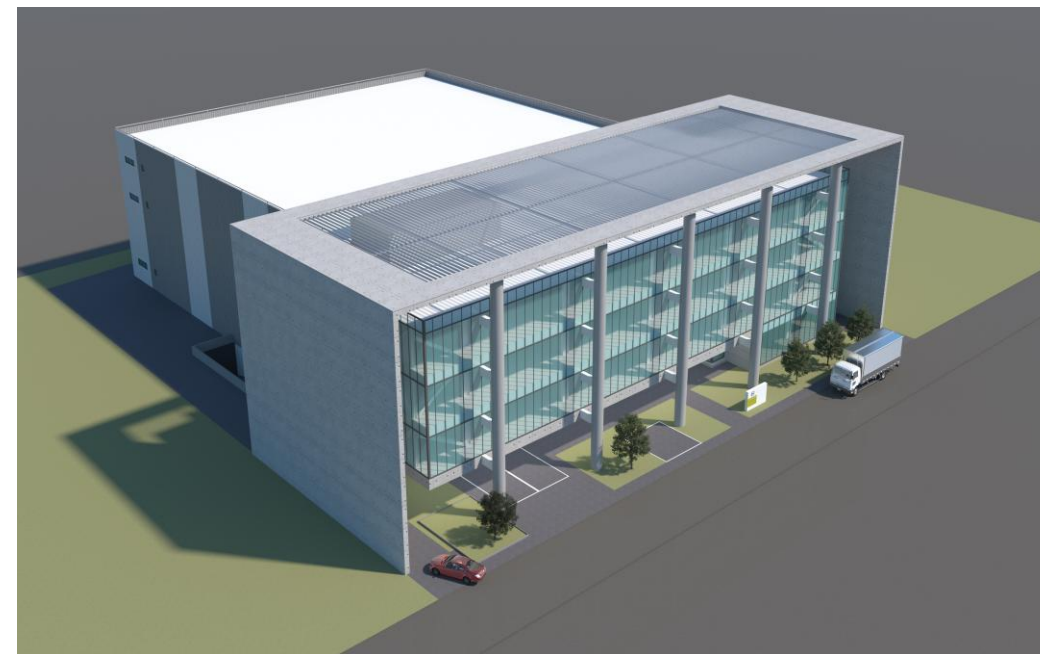


Expansion Roadmap

- 2023: New equipment production base in Hukou (off-site)
- 2024: Expansion of existing equipment production at Hukou Plant
- **2025 Q4: Wafer Reclaim Capacity 50K/Month at Hukou Plant**
- **2026 Q1: New Office in Shanghai**
- **2026 Q4: Wafer Reclaim Capacity 40K/Month at Hukou Plant**
- **Acquisition: YAYATECH (亞亞) in 2025, Nutrim (新群) in 2026**
- 2027: Wafer Reclaim Capacity 50K/Month at Hukou Plant

Expansion Roadmap

- **2026 Q4: 9,000 M² (2,700坪)** new building (Plant II) for EQPT MFG, and Warehouse next to Hukou Plant I
- **2028 Q1: 22,000 M² (6,600坪)** new building for EQPT MFG, Office and Warehouse in Tainan



Capex / Investment

Capex	NTD K	USD K
Wafer Reclaim 50K Expansion	1,450,000	48,000
Wafer Reclaim 40K Expansion	300,000	10,000
Shanghai Office	180,000	6,000
Hukou Factory II	550,000	18,000
Tainan Factory	850,000	31,000
Sum	3,305,000	113,000

Capex	2024	2025	2026
NTD K	546,000	1,250,000	1,750,000
USD K	18,000	41,000	58,000

Other Invest.	2024	2025	2026
NTD K	215,000	109,000	43,000
USD K	7,000	3,600	1,400

Key Highlights

- **Semiconductor CAGR to support our aggressive investment.**
- **Semiconductor Market Size**
 - **2024: 640B**
 - **2025: 750B**
 - **2026: 900B – 1Trillion**
- **TSMC's earning call:**
 - **CAGR for AI Accelerator Chips raised from mid-40% to mid-to-high 50% range during 2024-2029**
 - **Total revenue CAGR raised from 20% to 25% during 2024 to 2029**

Excellent Production Support

TSMC 2024 Outstanding Suppliers Award



<https://pr.tsmc.com/english/news/3192>



SCIENTECH

Thank You!

<https://www.scientech.com.tw>